

Lead Free No Clean Solder Paste NEW**4900P**[BUY NOW](#)

MG Chemicals has developed a unique flux system designed specifically for high temperature lead free alloys. It provides the fluxing activity levels that promote thermal stability and prevents thermal degradation when reflowing under air atmosphere (normal). Since use of nitrogen is not required, MG 4900P Lead Free Solder paste will provide excellent cost savings.

In addition, MG 4900P Lead Free solder paste exhibits superior joint strength, excellent wettability, and extraordinary print definition and tack life. The post soldering residues of MG 4900P are non-conductive, non-corrosive and highly insulated.

Features & Benefits

- Low residues
- Easily dispensed
- Long tack-time
- Excellent wettability
- Hard non-conductive residues



Catalog Number	Sizes Available	Description
4900P-25G	25 grams	Paste
4900P-250G	250 grams	Paste